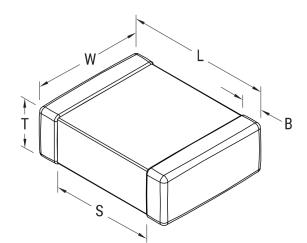


C0805X331J1GACTU

Aliases (C0805X331J1GAC7800)

SMD Comm COG Flex, Ceramic, 330 pF, 5%, 100 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	0.75mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm COG Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications		
Capacitance	330 pF	
Measurement Condition	1 MHz 1.0Vrms	
Capacitance Tolerance	5%	
Voltage DC	100 VDC	
Dielectric Withstanding Voltage	250 VDC	
Temperature Range	-55/+125°C	
Temperature Coefficient	COG	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms	
Dissipation Factor	0.1% 1 MHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour	
Insulation Resistance	100 GOhms	

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